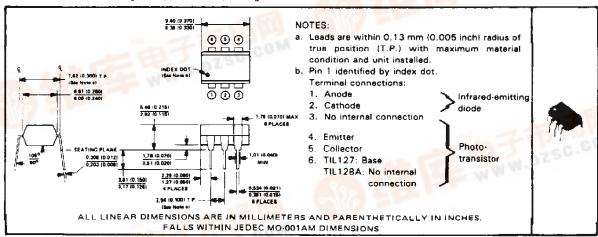
TIL127, TIL128A **OPTOCOUPLERS**

SOOS045A D2328, MAY 1977-REVISED JUNE 1989

- WWW.DZSG.COM Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N **Darlington-Connected Phototransistor**
- High Direct-Current Transfer Ratio . . . 300% Minimum at 10 mA
- High-Voltage Electrical Isolation . . . 5000-Volt Rating
- Plastic Dual-In-Line Package
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers
- No Base Connection on TIL 128A for Environments with High Electromagnetic Interference

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation, and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input to Output Voltage	5 kV									
Collector-Base Voltage (TIL127)	30 V									
Collector-Emitter Voltage (See Note 1)	30 V									
Emitter-Collector Voltage	7 V									
Emitter-Base Voltage (TIL127)	7 V									
Input-Diode Reverse Voltage	3 V									
Input-Diode Continuous Forward Current	mΑ									
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:										
Infrared-Emitting Diode (See Note 2)	mW									
Phototransistor (See Note 3)	mW									
Total (Infrared-Emitting Diode plus Phototransistor, See Note 4)	mW									
Storage Temperature Range	i0°C									
Lead Temperature 1,6 mm (1/16 Inch) from Case for 10 Seconds	60°C									

- NOTES: 1. This value applies when the base-emitter diode is open-circuited
 - 2 Derate linearly to 100°C free-pir temperature at the rate of 2 mW/°C.
 - 3. Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C.
 - 4. Denate linearly to 100°C free-air temperature at the rate of 3.33 mW/°C.

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TIL127, TIL128A OPTOCOUPLERS

electrical characteristics at 25°C free-air temperature

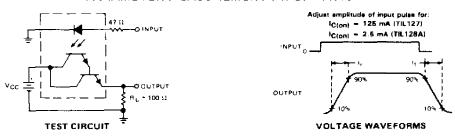
DAC		TEST COMPLYIONS!			TIL127			1	UNIT		
PARAMETER		TEST CONDITIONS [†]			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
V(BR)CBO	Collector-Base Breakdown Voltage	I _C = 10 μA,	IE = 0,	le = 0	30						v
V(BRICEO	Collector-Emitter Breakdown Voltage	I _C = 1 mA,	I _B ≠ 0.	iF = 0	30			30			٧
Vівятєво	Emitter-Base Breakdown Voltage	IE = 10 μA,	IC = 0'	1F = 0	7						V
V(BR)ECO	Emitter-Collector Breakdown Voltage	IE = 10 μA,	1E = 0					7			٧
IR	Input Diode Static Reverse Current	V _H = 3 V					10			10	μА
^I Clan)	On-State	V _{CE} = 1 V,	1B = 0'	Ip = 10 mA	30	100					mΑ
	Collector Current		IF = 10 mA					30	160		
IC(off)	Off-State Collector Current	V _{CE} = 10 V,	I _B = 0,	IF = 0			100			100	n A
hFE	Transistor Static Forward Current Transfer Ratio	V _{CE} = 1 V,	I _C 10 mA,	1 _F - 0	,	5 000					
۷Ę	Input Diode Static Forward Voltage	l _F = 10 mA					1.5			1.5	V
	Collector-Emitter	Ic 125 mA,	I _B = 0,	I _F = 50 mA			1.2	1		-	.,
VCE(sat)	Saturation Voltage	IC = 30 mA,	IF = 10 mA		<u> </u>		··· -	1		1	V
rio	Input-to-Output Internal Resistance	V _{in-out} = 500 V,	See Note 5		1011			10 ¹¹	· <u></u>	- 	Ω
c _{io}	Input-to-Output Capacitance	V _{in-out} = 0,	f = 1 MHz,	See Note 5		1	1,3		1	1.3	рF

NOTE 5: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together. [†]References to the base are not applicable to the TIL128A.

switching characteristics at 25°C free-air temperature

DADAMETER	TER	TEST CONDITIONS†		TIL127			TIL128A			
PARAMETER		163	TEST CONDITIONS.			MAX	MIN	TYP	MAX	UNIT
tr	Rise Time	V _{CC} = 15 V,	I _{C(оп)} = 125 mA,		300					
tf	Fall Time	R _L = 100 Ω,	See Figure 1		300					μs
tŗ	Rise Time	V _{CC} = 10 V,	$I_{C(on)} = 2.5 \text{ mA},$					300		
tf	Fall Time	R _L = 100 Ω,	See Figure 1				_	300		μ5

PARAMETER MEASUREMENT INFORMATION



- NOTES: a. The input waveform is supplied by a generator with the following characteristics: $Z_{\text{out}} = 50 \, \Omega$, $t_r \leqslant 15 \, \text{ns}$, duty cycle $\approx 1\%$, $t_W \approx 500 \, \mu\text{s}$.

 b. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r \leqslant 12 \, \text{ns}$, $R_{\text{int}} \ge 1 \, \text{M}\Omega$, $C_{\text{int}} \leqslant 20 \, \text{pF}$.

FIGURE 1-SWITCHING TIMES

TYPICAL CHARACTERISTICS

COLLECTOR CURRENT COLLECTOR-EMITTER VOLTAGE 120 Onice Office of the Constitution of the Consti l_B ≈ 'n 10 EUR) TA = 25°C 100 See Note 6 IC-Collector Current-mA 80 60 40 2,5 mA ۱F 20 0 0 2.0 2.4 0.4 0.8 1.2 1.6 VCE-Collector-Emitter Voltage-V

FIGURE 2

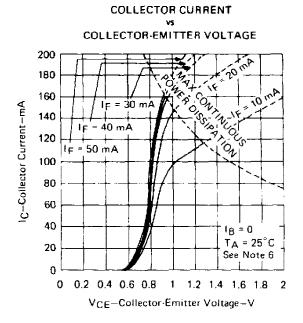
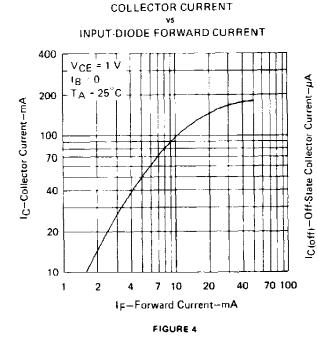


FIGURE 3



OFF-STATE COLLECTOR CURRENT FREE-AIR TEMPERATURE 1000

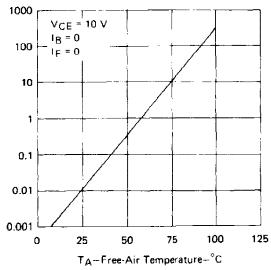


FIGURE 5

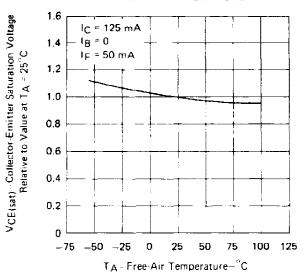
NOTE 6: Pulse operation of input diode is required for operation beyond limits shown by dotted line.



TYPICAL CHARACTERISTICS

RELATIVE COLLECTOR-EMITTER SATURATION VOLTAGE vs

FREE AIR TEMPERATURE



TIL127 TRANSISTOR STATIC FORWARD CURRENT TRANSFER RATIO vs

COLLECTOR CURRENT

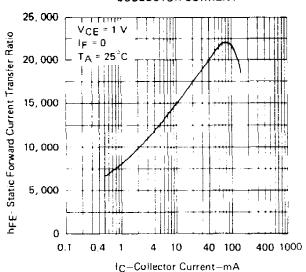
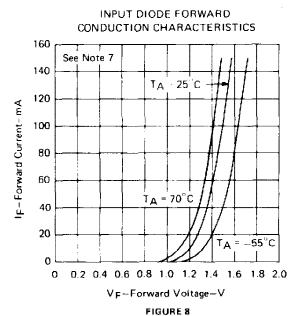


FIGURE 6

FIGURE 7



NOTE 7: This parameter was measured using pulse techniques, t_w = 1 ms, duty cycle < 2%.



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